

CIRCUIT BOARD HAVING IMPROVED  
SOLDERING CHARACTERISTICS

ABSTRACT OF THE DISCLOSURE

5 A circuit board having improved soldering  
characteristics having raised structure consisting of spacer  
pads arranged to provide for vertical distancing of electrical  
or electronic components from the component side planar  
surface of the circuit board. Such spacing is complementary  
to top vented soldering stations where the spacing allows  
10 solder process gases to flow unimpeded from the soldering  
stations through the spacing to atmosphere.

TOP SECRET

# CIRCUIT BOARD HAVING IMPROVED SOLDERING CHARACTERISTICS

## PARTS LIST

10	circuit board having improved soldering characteristics	34	upper surface
		38	hole
		38a	hole
10a	circuit board having improved soldering characteristics	40	barrel
		42	upper tinned layer
12	substrate	44	foil member
14	stand alone spacer pad	46	lower plastic mask
		48	lower tinned layer
16	stand alone spacer pad	50	LED
18	terminal spacer pad	52	bottom surface
		54	upper surface
20	solder station	55	space
20a	solder station	55a	space
22	terminal spacer pad	56	passage
		56a	passage
24	solder station	58	lead
24a	solder station	60	solder
26	upper plastic mask	62	gases
26a-b	raised plastic mask portions	64a-n	arrows
28a-b	foil members		
30	upper surface		